

SYTFB050ND4S

5.0GHz Surface Mount Bandpass Filter

Frequency Range

(GHz)

4.5 - 5.5

DC - 3.65

6.15 - 12.0

*Electrical specifications based on typical probed performance at room temperature. Insertion loss shall vary ±0.5dB over temperature.

**Power rating assumes the component will be mounted to a PCB with good thermally conducting ground vias as outlined in the recommended PCB layout that are connected to an adequate heat

Min

5

0.350 x 0.200 x 0.090 in

8.89 x 5.08 x 2.29 mm

Тур.

2.0

12.0

45.0

42.0

Max

2.25

10.0

40.0

40.0

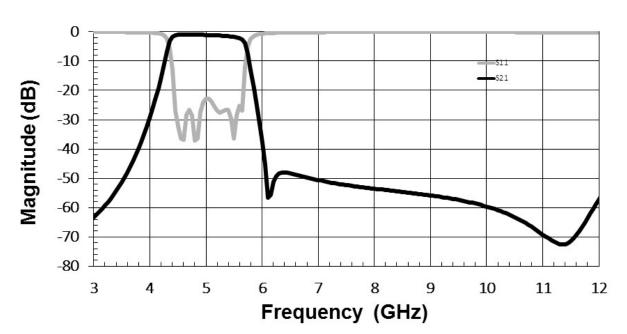
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Description

Yantel's surface mount catalog bandpass filters utilize Yantel's low loss temperature stable materials which offer small size and minimal performance variation over temperature. The catalog BPF's are offered in a variety of frequency bands, which offers a drop in solution with highly repeatable performance.

Features

- Small Size
- Fully Shielded Component
- Solder Surface Mount Package
- Moisture Sensitivity Level: MSL1
- Frequency Stable over Temperature
- Operating & Storage Temp: -55°C to +125°C
- Characteristic Impedance: 50Ω



Specifications*

Parameter

Insertion Loss

(dB)

Return Loss

(dB)

Low Side

Rejection (dB) High Side

Rejection (dB)

CW Input

Power** (W)

Size (L x W x H)

sink. Max power is based on 125°C base temperature.

Typical Measured Performance

*Typical de-embedded measured performance mounted on a connectorized test fixture. DEB is 0.254mm RO4350B with 50.00hm CPW ground traces going into the ports at room temperature.



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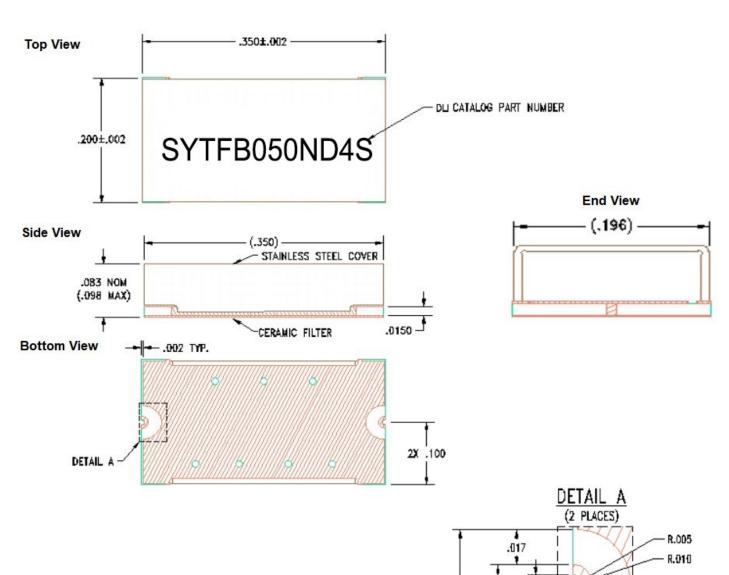
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Physical Dimensions

Units = inches



Notes :

1. Termination Finish:

ENIG: 3 - 6 µinch Au over 50 µinch Ni

2. Maximum Assembly Process Temperature: 250°C

Tolerances:

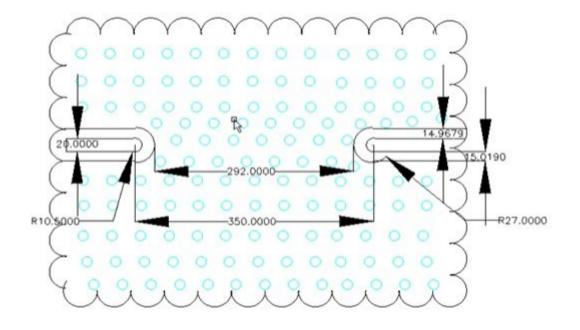
For values with 3 decimal places ± 0.001 For values with 4 decimal places ± 0.0005 R.027



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Recommended PCB Layout



Units = mils

Note:

- 50Ω trace dimensions are application specific.
- Ensure adequate grounding beneath the part.